

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
< 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
> 2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Latch-Up Performance Exceeds 250 mA
Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need
for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil
Shrink Small-Outline (DL) and Thin Shrink
Small-Outline (DGG) Packages

DESCRIPTION

This 16-bit edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC16374 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

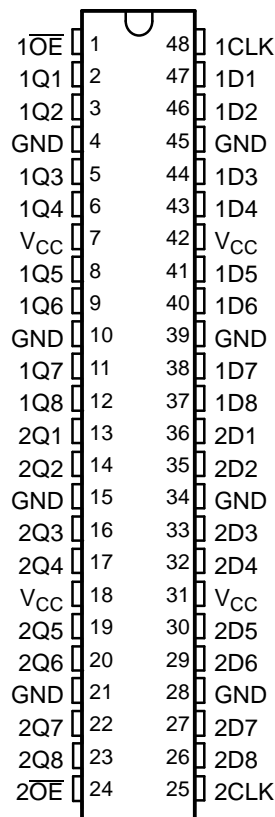
\overline{OE} does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVC16374 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE
(TOP VIEW)



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SN74LVC16374

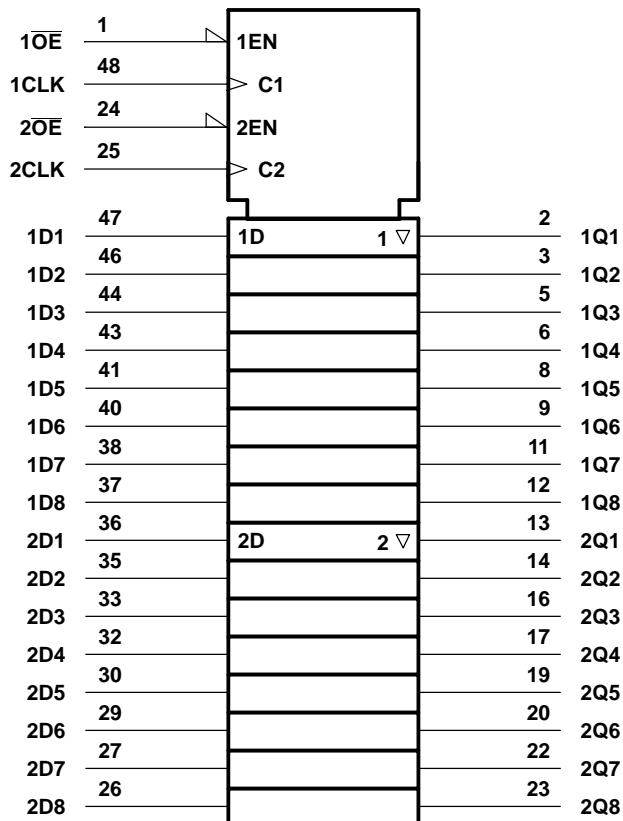
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS316B—NOVEMBER 1993—REVISED MARCH 2005

FUNCTION TABLE (EACH FLIP-FLOP)

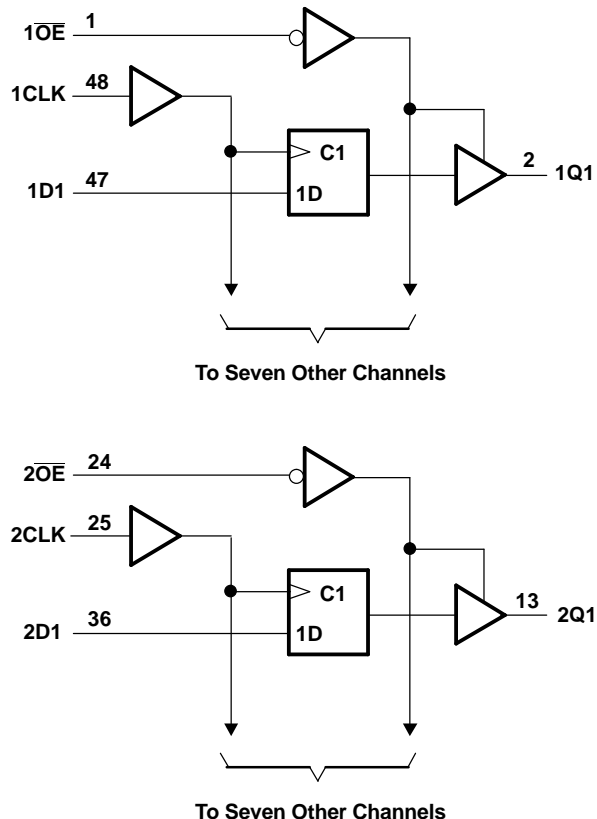
INPUTS			OUTPUT Q
\overline{OE}	CLK	D	
L	\uparrow	H	H
L	\uparrow	L	L
L	H or L	X	Q_0
H	X	X	Z

LOGIC SYMBOL⁽¹⁾



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		−0.5	4.6	V
V _I	Input voltage range ⁽²⁾		−0.5	4.6	V
V _O	Output voltage range ⁽²⁾⁽³⁾		−0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	−50		mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{CC}	±50		mA
I _O	Continuous output current	V _O = 0 to V _{CC}	±50		mA
Continuous current through V _{CC} or GND			±100		mA
Maximum power dissipation at T _A = 55°C (in still air) ⁽⁴⁾		DGG package	0.85		W
		DL package	1.2		
T _{stg}	Storage temperature range		−65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2		V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8	V
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2.7\text{ V}$		–12	mA
		$V_{CC} = 3\text{ V}$		–24	
I_{OL}	Low-level output current	$V_{CC} = 2.7\text{ V}$		12	mA
		$V_{CC} = 3\text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		–40	85	$^\circ\text{C}$

- (1) Unused control inputs must be held high or low to prevent them from floating.

SN74LVC16374

16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS316B–NOVEMBER 1993–REVISED MARCH 2005

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC} ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}		I _{OH} = −100 μA	MIN to MAX	V _{CC} − 0.2			V
		I _{OH} = −12 mA	2.7 V	2.2			
			3 V	2.4			
		I _{OH} = −24 mA	3 V	2			
V _{OL}		I _{OL} = 100 μA	MIN to MAX			0.2	V
		I _{OL} = 12 mA	2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
I _I		V _I = V _{CC} or GND	3.6 V			±5	μA
I _{I(hold)}	Data inputs	V _I = 0.8 V	3 V	75			μA
		V _I = 2 V		−75			
			V _I = 0 to 3.6 V	3.6 V			
I _{OZ}		V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			40	μA
ΔI _{CC}		One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			500	μA
C _i		V _I = V _{CC} or GND	3.3 V	3.5			pF
C _o		V _O = V _{CC} or GND	3.3 V	7			pF

(1) For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

(2) All typical values are at $V_{CC} = 3.3\ V$, $T_A = 25^\circ C$.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

			$V_{CC} = 3.3\ V$ $\pm 0.3\ V$		$V_{CC} = 2.7\ V$		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	100	0	80	MHz
t_w	Pulse duration, CLK high or low		4		4		ns
t_{su}	Setup time, data before CLK \uparrow	High or low	2		3		ns
t_h	Hold time, data after CLK \uparrow	High or low	1.5		1.5		ns

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50\ pF$ (unless otherwise noted) (see Figure 1)

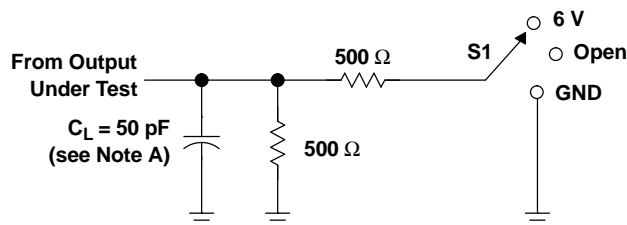
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\ V$ $\pm 0.3\ V$		$V_{CC} = 2.7\ V$		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			100		80		MHz
t_{pd}	CLK	Q	1.5	7.5	1.5	8.5	ns
t_{en}	\overline{OE}	Q	1.5	7.5	1.5	8.5	ns
t_{dis}	\overline{OE}	Q	1.5	7	1.5	8	ns

Operating Characteristics

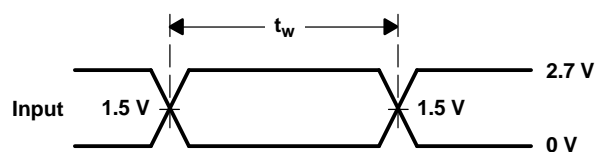
$V_{CC} = 3.3\ V$, $T_A = 25^\circ C$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	$C_L = 50\ pF$, $f = 10\ MHz$	22	pF
	Outputs disabled		9	

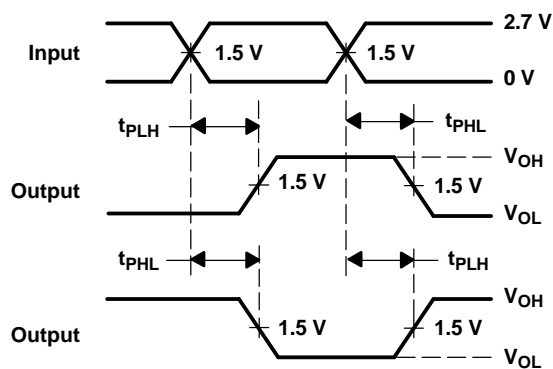
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR OUTPUTS

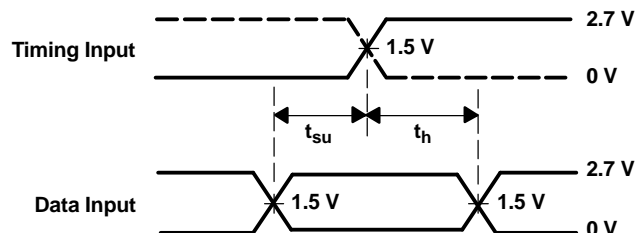


VOLTAGE WAVEFORMS
PULSE DURATION

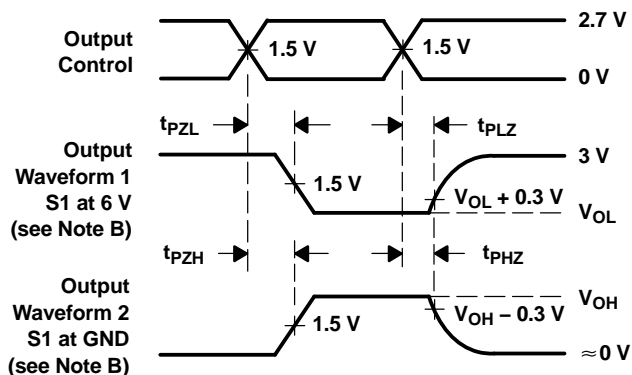


VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LVC16374DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374
SN74LVC16374DGGR.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374
SN74LVC16374DL	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374
SN74LVC16374DL.B	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374
SN74LVC16374DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374
SN74LVC16374DLR.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16374

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC16374DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74LVC16374DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC16374DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74LVC16374DLR	SSOP	DL	48	1000	356.0	356.0	53.0

TUBE

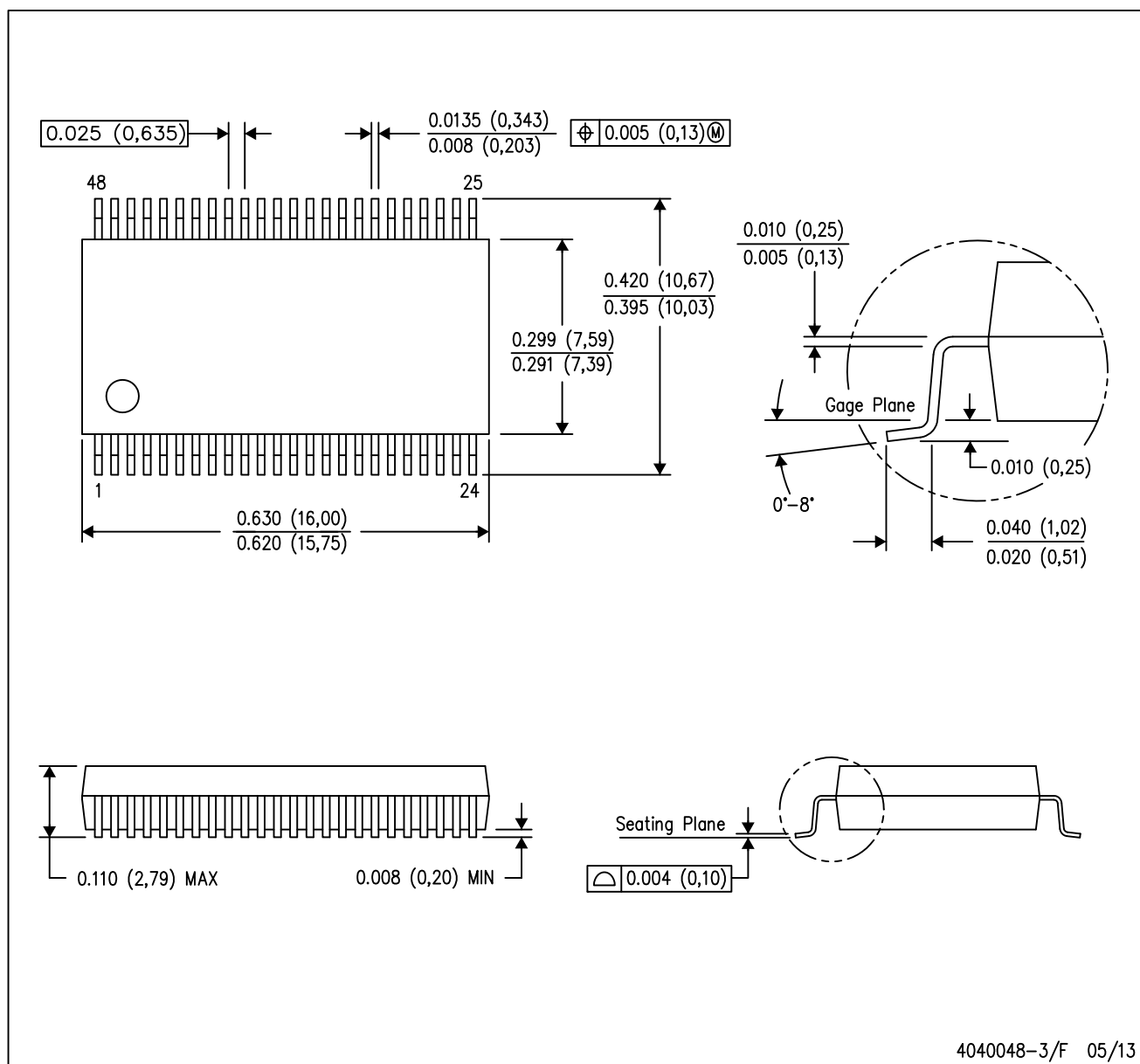


*All dimensions are nominal

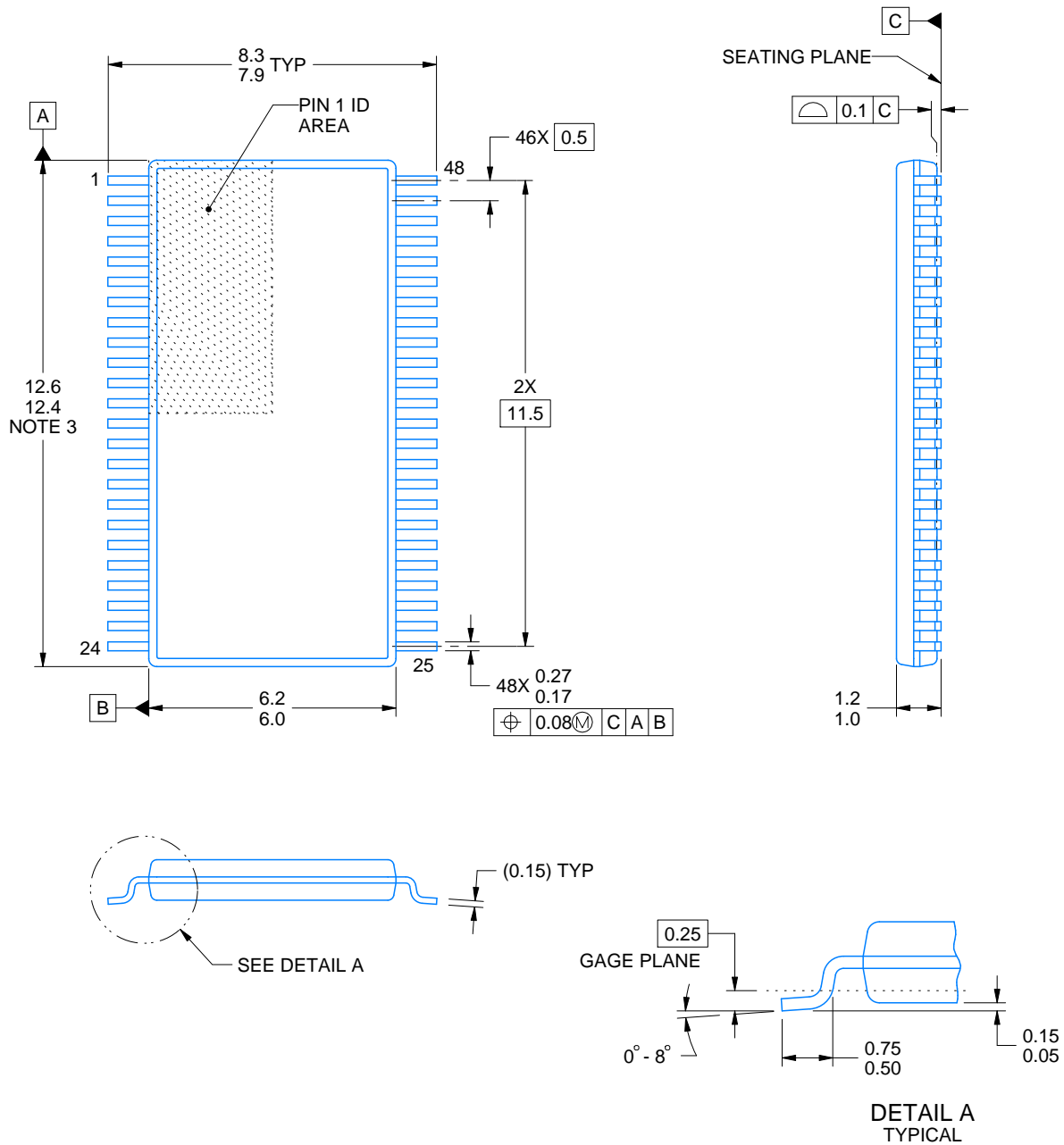
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVC16374DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74LVC16374DL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118



4214859/B 11/2020

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

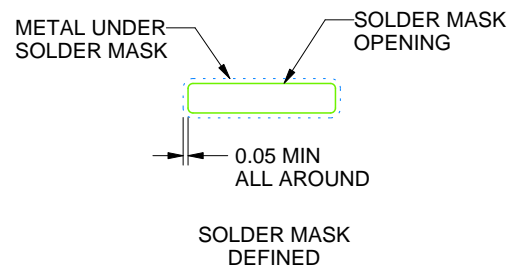
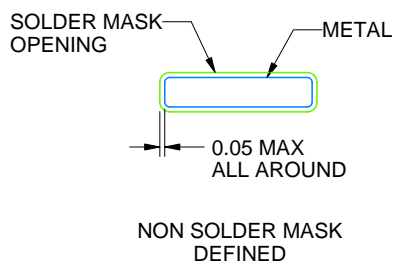
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

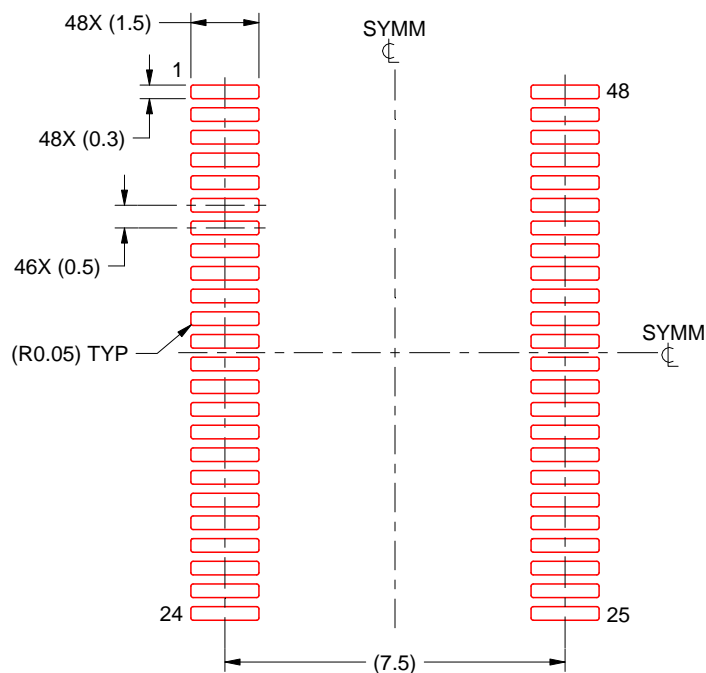
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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